

LM397 Single General Purpose Voltage Comparator

Check for Samples: [LM397](#)

FEATURES

- ($T_A = 25^\circ\text{C}$. Typical Values Unless Otherwise Specified).
- 5-Pin SOT-23 Package
- Industrial Operating Range -40°C to $+85^\circ\text{C}$
- Single or Dual Power Supplies
- Wide Supply Voltage Range 5V to 30V
- Low Supply Current 300 μA
- Low Input Bias Current 7nA
- Low Input Offset Current $\pm 1\text{nA}$
- Low Input Offset Voltage $\pm 2\text{mV}$
- Response Time 440ns (50mV Overdrive)
- Input Common Mode Voltage 0 to $V_S - 1.5\text{V}$

APPLICATIONS

- A/D Converters
- Pulse, Square Wave Generators
- Peak Detector
- Industrial Applications

Connection Diagram

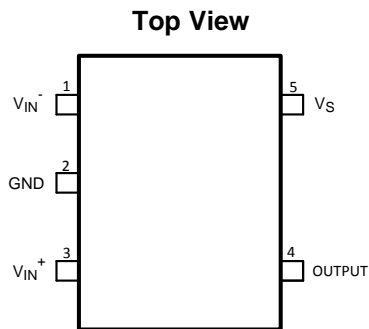


Figure 1. 5-Pin SOT-23 Package
See Package Number DBV0005A

DESCRIPTION

The LM397 is a single voltage comparator with an input common mode that includes ground. The LM397 is designed to operate from a single 5V to 30V power supply or a split power supply. Its low supply current is virtually independent of the magnitude of the supply voltage.

The LM397 features an open collector output stage. This allows the connection of an external resistor at the output. The output can directly interface with TTL, CMOS and other logic levels, by tying the resistor to different voltage levels (level translator).

The LM397 is available in space saving 5-Pin SOT-23 package and pin compatible to TI's TL331, single differential comparator.

Typical Circuit

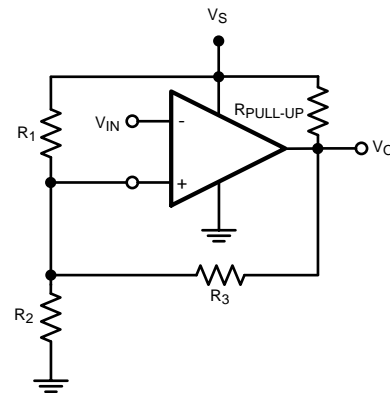


Figure 2. Inverting Comparator with Hysteresis



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.



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Absolute Maximum Ratings⁽¹⁾⁽²⁾

| | | |
|-------------------------------------|----------------------------------|-----------------|
| ESD Tolerance ⁽³⁾ | Human Body Model | 2KV |
| | Machine Model | 200V |
| V _{IN} Differential | | 30V |
| Supply Voltages | | 30V or ±15V |
| Voltage at Input Pins | | -0.3V to 30V |
| Storage Temperature Range | | -65°C to +150°C |
| Junction Temperature ⁽⁴⁾ | | +150°C |
| Soldering Information | Infrared or Convection (20 sec.) | 235°C |
| | Wave Soldering (10 sec.) | 260°C |

- (1) Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is intended to be functional, but specific performance is not ensured. For ensured specifications and the test conditions, see the Electrical Characteristics.
- (2) If Military/Aerospace specified devices are required, please contact the TI Sales Office/ Distributors for availability and specifications.
- (3) Human Body Model, applicable std. MIL-STD-883, Method 3015.7. Machine Model, applicable std. JESD22-A115-A (ESD MM std. of JEDEC) Field-Induced Charge-Device Model, applicable std. JESD22-C101-C (ESD FICDM std. of JEDEC).
- (4) The maximum power dissipation is a function of T_{J(MAX)}, θ_{JA}. The maximum allowable power dissipation at any ambient temperature is P_D = (T_{J(MAX)} - T_A) / θ_{JA}. All numbers apply for packages soldered directly onto a PC board.

Operating Ratings⁽¹⁾

| | | |
|-------------------------------------------|--------------|----------------|
| Supply Voltage, V _S | | 5V to 30V |
| Temperature Range ⁽²⁾ | | -40°C to +85°C |
| Package Thermal Resistance ⁽²⁾ | 5-Pin SOT-23 | 168°C/W |

- (1) Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is intended to be functional, but specific performance is not ensured. For ensured specifications and the test conditions, see the Electrical Characteristics.
- (2) The maximum power dissipation is a function of T_{J(MAX)}, θ_{JA}. The maximum allowable power dissipation at any ambient temperature is P_D = (T_{J(MAX)} - T_A) / θ_{JA}. All numbers apply for packages soldered directly onto a PC board.

Electrical Characteristics

Unless otherwise specified, all limits are ensured for $T_A = 25^\circ\text{C}$, $V_S = 5\text{V}$, $V^- = 0\text{V}$, $V_{\text{CM}} = V^+/2 = V_O$. **Boldface** limits apply at the temperature extremes.

| Parameter | | Test Conditions | Min ⁽¹⁾ | Typ ⁽²⁾ | Max ⁽¹⁾ | Units |
|----------------------|---------------------------------|-----------------------------------------------------------------------------------------------------------------------|--------------------|--------------------|------------------------------------------------------------|---------------|
| V_{OS} | Input Offset Voltage | $V_S = 5\text{V to } 30\text{V}$, $V_O = 1.4\text{V}$, $V_{\text{CM}} = 0\text{V}$ | | 2 | 7 10 | mV |
| I_{OS} | Input Offset Current | $V_O = 1.4\text{V}$, $V_{\text{CM}} = 0\text{V}$ | | 1.6 | 50 250 | nA |
| I_{B} | Input Bias Current | $V_O = 1.4\text{V}$, $V_{\text{CM}} = 0\text{V}$ | | 10 | 250 400 | nA |
| I_{S} | Supply Current | $R_{\text{L}} = \text{Open}$, $V_S = 5\text{V}$ | | 0.25 | 0.7 | mA |
| | | $R_{\text{L}} = \text{Open}$, $V_S = 30\text{V}$ | | 0.30 | 2 | |
| I_{O} | Output Sink Current | $V_{\text{IN}^+} = 1\text{V}$, $V_{\text{IN}^-} = 0\text{V}$, $V_O = 1.5\text{V}$ | 6 | 13 | | mA |
| I_{LEAKAGE} | Output Leakage Current | $V_{\text{IN}^+} = 1\text{V}$, $V_{\text{IN}^-} = 0\text{V}$, $V_O = 5\text{V}$ | | 0.1 | | nA |
| | | $V_{\text{IN}^+} = 1\text{V}$, $V_{\text{IN}^-} = 0\text{V}$, $V_O = 30\text{V}$ | | 1 | | μA |
| V_{OL} | Output Voltage Low | $I_{\text{O}} = -4\text{mA}$, $V_{\text{IN}^+} = 0\text{V}$, $V_{\text{IN}^-} = 1\text{V}$ | | 180 | 400 700 | mV |
| V_{CM} | Common-Mode Input Voltage Range | $V_S = 5\text{V to } 30\text{V}^{(3)}$ | 0 0 | | $V_S - 1.5\text{V}$ $V_S - 2\text{V}$ | V |
| A_{V} | Voltage Gain | $V_S = 15\text{V}$, $V_O = 1.4\text{V to } 11.4\text{V}$, $R_{\text{L}} > = 15\text{k}\Omega$ connected to V_S | | 120 | | V/mV |
| t_{PHL} | Propagation Delay (High to Low) | Input Overdrive = 5mV $R_{\text{L}} = 5.1\text{k}\Omega$ connected to 5V, $C_{\text{L}} = 15\text{pF}$ | | 900 | | ns |
| | | Input Overdrive = 50mV $R_{\text{L}} = 5.1\text{k}\Omega$ connected to 5V, $C_{\text{L}} = 15\text{pF}$ | | 250 | | |
| t_{PLH} | Propagation Delay (Low to High) | Input Overdrive = 5mV $R_{\text{L}} = 5.1\text{k}\Omega$ connected to 5V, $C_{\text{L}} = 15\text{pF}$ | | 940 | | μs |
| | | Input Overdrive = 50mV $R_{\text{L}} = 5.1\text{k}\Omega$ connected to 5V, $C_{\text{L}} = 15\text{pF}$ | | 440 | | ns |

- (1) All limits are specified by testing or statistical analysis.
- (2) Typical values represent the most likely parametric norm as determined at the time of characterization. Actual typical values may vary over time and will also depend on the application and configuration. The typical values are not tested and are not specified on shipped production material.
- (3) The input common-mode voltage of either input should not be permitted to go below the negative rail by more than 0.3V. The upper end of the common-mode voltage range is $V_S - 1.5\text{V}$ at 25°C .

Typical Performance Characteristics

T_A = 25°C. Unless otherwise specified.

Supply Current vs. Supply Voltage

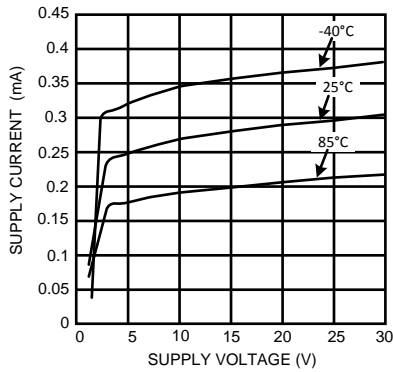


Figure 3.

Input Bias Current vs. Supply Current

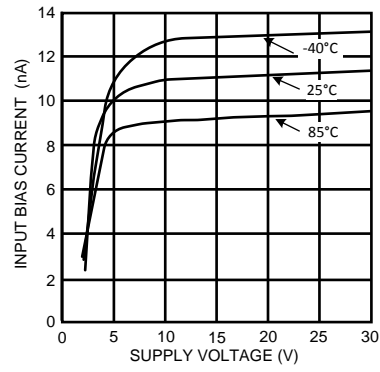


Figure 4.

Output Saturation Voltage vs. Output Sink Current

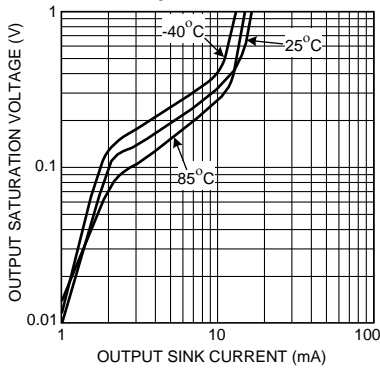


Figure 5.

Input Offset Voltage vs. Supply Voltage

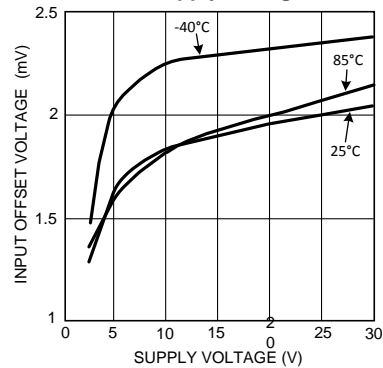


Figure 6.

Response Time for Various Input Overdrives – t_{PHL}

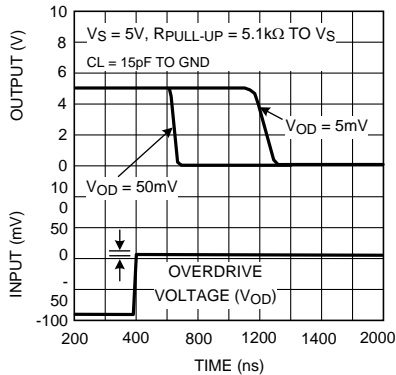


Figure 7.

Response Time for Various Input Overdrives – t_{PLH}

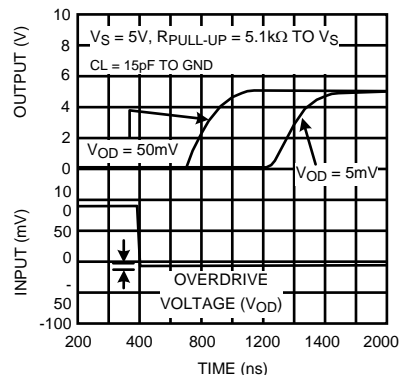


Figure 8.

APPLICATION NOTES

Basic Comparators

A comparator is quite often used to convert an analog signal to a digital signal. The comparator compares an input voltage (V_{IN}) at the non-inverting pin to the reference signal (V_{REF}) at the inverting pin. If V_{IN} is less than V_{REF} the output (V_O) is low (V_{OL}). However, if V_{IN} is greater than V_{REF} , the output voltage (V_O) is high (V_{OH}). Refer to [Figure 9](#).

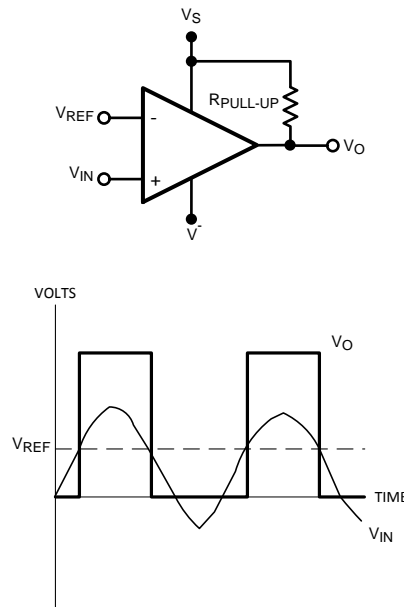


Figure 9. Basic Comparator

Hysteresis

The basic comparator configuration may oscillate or produce a noisy output if the applied differential input is near the comparator's input offset voltage. This tends to occur when the voltage on the input is equal or very close to the other input voltage. Adding hysteresis can prevent this problem. Hysteresis creates two switching thresholds (one for the rising input voltage and the other for the falling input voltage). Hysteresis is the voltage difference between the two switching thresholds. When both inputs are nearly equal, hysteresis causes one input to effectively move quickly past the other. Thus, effectively moving the input out of region that oscillation may occur.

For an inverting configured comparator, hysteresis can be added with a three resistor network and positive feedback. When input voltage (V_{IN}) at the inverting node is less than non-inverting node (V_T), the output is high. The equivalent circuit for the three resistor network is R_1 in parallel with R_3 and in series with R_2 . The lower threshold voltage V_{T1} is calculated by:

$$V_{T1} = ((V_S R_2) / (((R_1 R_3) / (R_1 + R_3)) + R_2)) \quad (1)$$

When V_{IN} is greater than V_T , the output voltage is low. The equivalent circuit for the three resistor network is R_2 in parallel with R_3 and in series with R_1 . The upper threshold voltage V_{T2} is calculated by:

$$V_{T2} = V_S ((R_2 R_3) / (R_2 + R_3)) / (R_1 + ((R_2 R_3) / (R_2 + R_3))) \quad (2)$$

The hysteresis is defined as

$$\Delta V_{IN} = V_{T1} - V_{T2} \quad (3)$$

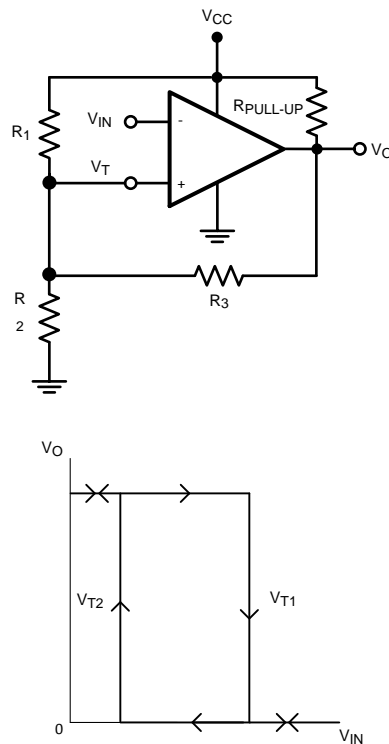


Figure 10. Inverting Configured Comparator - LM397

Input Stage

The LM397 has a bipolar input stage. The input common mode voltage range is from 0 to $(V_S - 1.5V)$.

Output Stage

The LM397 has an open collector grounded-emitter NPN output transistor for the output stage. This requires an external pull-up resistor connected between the positive supply voltage and the output. The external pull-up resistor should be high enough resistance so to avoid excessive power dissipation. In addition, the pull-up resistor should be low enough resistance to enable the comparator to switch with the load circuitry connected. Because it is an open collector output stage, several comparator outputs can be connected together to create an OR'ing function output. With an open collector, the output can be used as a simple SPST switch to ground. The amount of current which the output can sink is approximately 10mA. When the maximum current limit is reached, the output transistor will saturate and the output will rise rapidly (Figure 11).

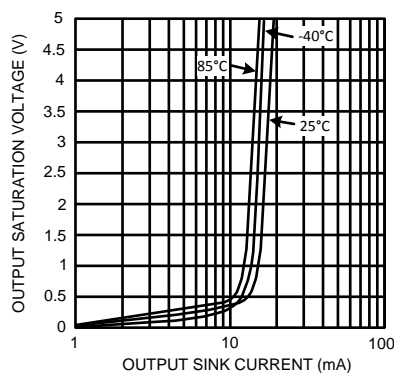


Figure 11. Output Saturation Voltage vs. Output Sink Current

REVISION HISTORY

| Changes from Revision C (March 2013) to Revision D | Page |
|------------------------------------------------------------|-------------------|
| • Changed layout of National Data Sheet to TI format | 6 |

PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|---------------|--------------|-----------------|------|-------------|-------------------------|-------------------------|----------------------|--------------|-------------------------|----------------|
| LM397MF | NRND | SOT-23 | DBV | 5 | 1000 | TBD | Call TI | Call TI | -40 to 85 | C397 | |
| LM397MF/NOPB | ACTIVE | SOT-23 | DBV | 5 | 1000 | Green (RoHS & no Sb/Br) | CU SN | Level-1-260C-UNLIM | -40 to 85 | C397 | Samples |
| LM397MFX/NOPB | ACTIVE | SOT-23 | DBV | 5 | 3000 | Green (RoHS & no Sb/Br) | CU SN | Level-1-260C-UNLIM | -40 to 85 | C397 | Samples |

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|---------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| LM397MF | SOT-23 | DBV | 5 | 1000 | 178.0 | 8.4 | 3.2 | 3.2 | 1.4 | 4.0 | 8.0 | Q3 |
| LM397MF/NOPB | SOT-23 | DBV | 5 | 1000 | 178.0 | 8.4 | 3.2 | 3.2 | 1.4 | 4.0 | 8.0 | Q3 |
| LM397MFX/NOPB | SOT-23 | DBV | 5 | 3000 | 178.0 | 8.4 | 3.2 | 3.2 | 1.4 | 4.0 | 8.0 | Q3 |

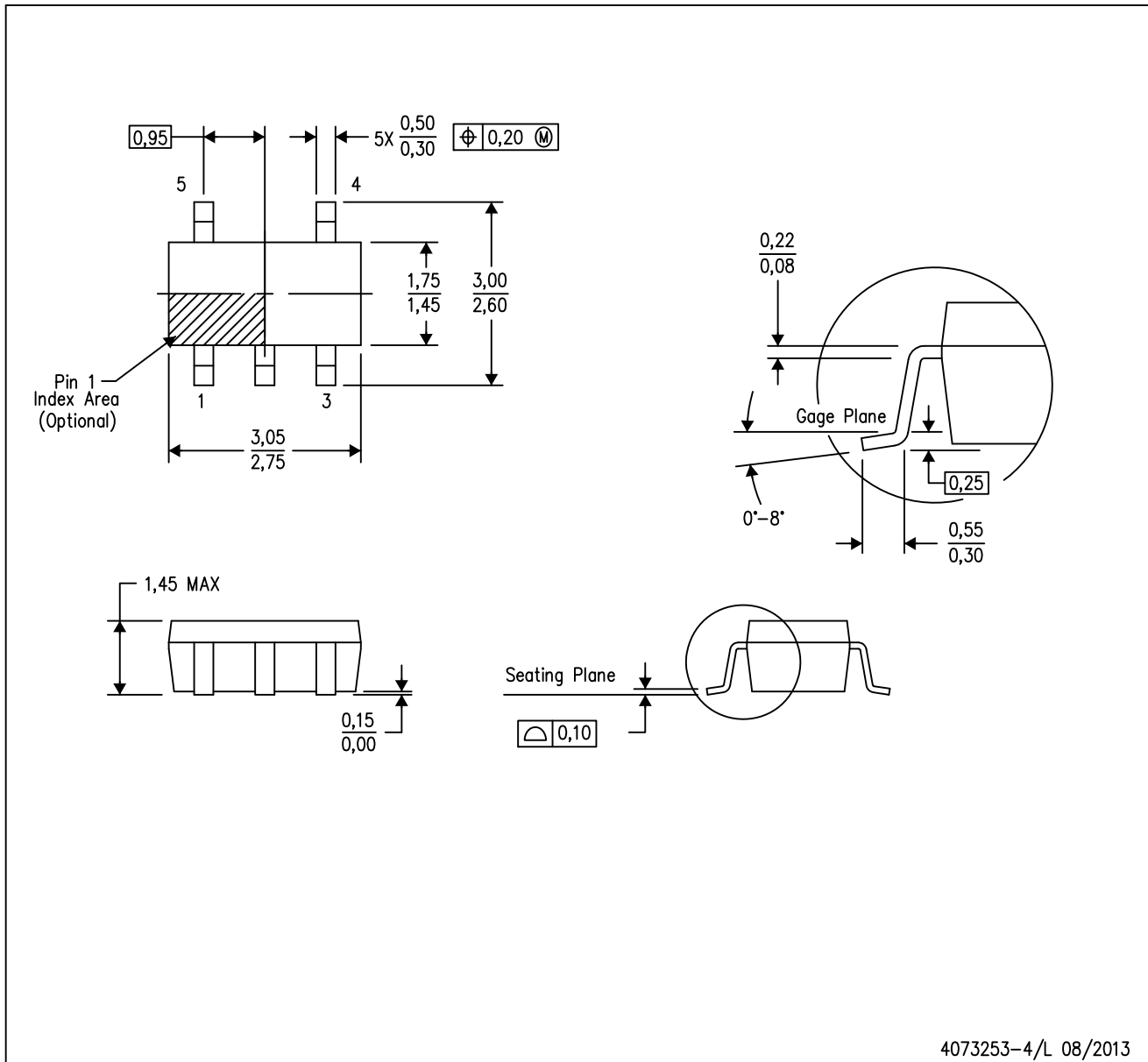
TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|---------------|--------------|-----------------|------|------|-------------|------------|-------------|
| LM397MF | SOT-23 | DBV | 5 | 1000 | 210.0 | 185.0 | 35.0 |
| LM397MF/NOPB | SOT-23 | DBV | 5 | 1000 | 210.0 | 185.0 | 35.0 |
| LM397MFX/NOPB | SOT-23 | DBV | 5 | 3000 | 210.0 | 185.0 | 35.0 |

DBV (R-PDSO-G5)

PLASTIC SMALL-OUTLINE PACKAGE



4073253-4/L 08/2013

- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
 - D. Falls within JEDEC MO-178 Variation AA.

DBV (R-PDSO-G5)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
 - D. Publication IPC-7351 is recommended for alternate designs.
 - E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.

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